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MMBFJ309L, MMBFJ310L, SMMBFJ309L, SMMBFJ309L

JFET - VHF/UHF Amplifier Transistor

N-Channel

Features

- Drain and Source are Interchangeable
- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Drain-Source Voltage	V _{DS}	25	Vdc
Gate-Source Voltage	V _{GS}	25	Vdc
Gate Current	I _G	10	mAdc

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR–5 Board, (Note 1) T _A = 25°C Derate above 25°C	P _D	225 1.8	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	556	°C/W
Junction and Storage Temperature	T _J , T _{stg}	-55 to +150	°C

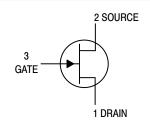
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. $FR-5 = 1.0 \times 0.75 \times 0.062$ in.



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SOT-23 (TO-236) CASE 318 STYLE 10

MARKING DIAGRAM



6x = Device Code

x = U for MMBFJ309L, SMMBFJ309L x = T for MMBFJ310L, SMMBFJ310L

M = Date Code*

= Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or overbar may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping [†]
MMBFJ309LT1G,	SOT-23	3,000 / Tape &
SMMBFJ309LT1G	(Pb-Free)	Reel
MMBFJ310LT1G,	SOT-23	3,000 / Tape &
SMMBFJ310LT1G	(Pb-Free)	Reel
SMMBFJ310LT3G	SOT-23 (Pb-Free)	10,000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MMBFJ309L, MMBFJ310L, SMMBFJ309L, SMMBFJ310L

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS	•				
Gate–Source Breakdown Voltage $(I_G = -1.0 \mu Adc, V_{DS} = 0)$	V _{(BR)GSS}	-25	-	-	Vdc
Gate Reverse Current ($V_{GS} = -15 \text{ Vdc}$) ($V_{GS} = -15 \text{ Vdc}$, $T_A = 125^{\circ}\text{C}$)	I _{GSS}	_ _	- -	-1.0 -1.0	nAdc μAdc
Gate Source Cutoff Voltage MMBFJ309 (V _{DS} = 10 Vdc, I _D = 1.0 nAdc) MMBFJ310, SMMBFJ310	G3(0II)	-1.0 -2.0	- -	-4.0 -6.5	Vdc
ON CHARACTERISTICS					
	500	12 24	_ _	30 60	mAdc
Gate-Source Forward Voltage (I _G = 1.0 mAdc, V _{DS} = 0)	V _{GS(f)}	_	-	1.0	Vdc
SMALL-SIGNAL CHARACTERISTICS					
Forward Transfer Admittance (V _{DS} = 10 Vdc, I _D = 10 mAdc, f = 1.0 kHz)	Y _{fs}	8.0	-	18	mmhos
Output Admittance (V _{DS} = 10 Vdc, I _D = 10 mAdc, f = 1.0 kHz)	y _{os}	-	-	250	μmhos
Input Capacitance (V _{GS} = -10 Vdc, V _{DS} = 0 Vdc, f = 1.0 MHz)	C _{iss}	-	-	5.0	pF
Reverse Transfer Capacitance (V _{GS} = -10 Vdc, V _{DS} = 0 Vdc, f = 1.0 MHz)	C _{rss}	-	_	2.5	pF
Equivalent Short–Circuit Input Noise Voltage (V _{DS} = 10 Vdc, I _D = 10 mAdc, f = 100 Hz)	e _n	-	10	-	nV/√Hz

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

MMBFJ309L, MMBFJ310L, SMMBFJ309L, SMMBFJ310L

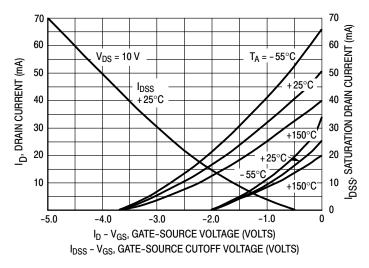


Figure 1. Drain Current and Transfer Characteristics versus Gate-Source Voltage

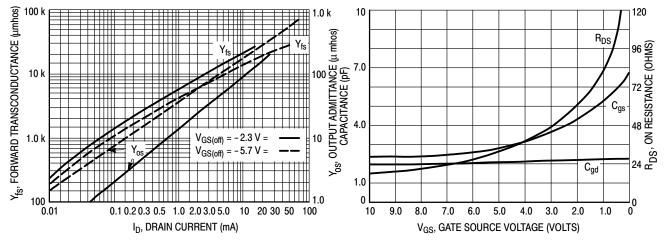


Figure 2. Common–Source Output
Admittance and Forward Transconductance
versus Drain Current

Figure 3. On Resistance and Junction Capacitance versus Gate-Source Voltage

MMBFJ309L, MMBFJ310L, SMMBFJ309L, SMMBFJ310L

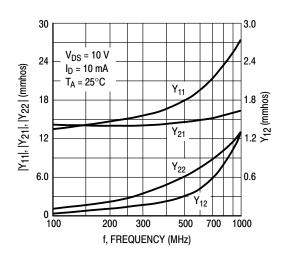


Figure 4. Common-Gate Y Parameter Magnitude versus Frequency

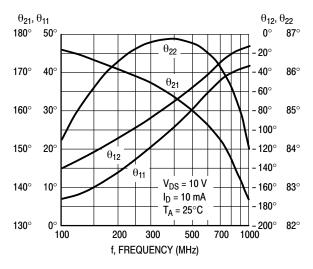


Figure 6. Common–Gate Y Parameter Phase–Angle versus Frequency

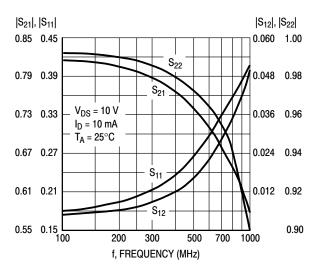


Figure 5. Common-Gate S Parameter Magnitude versus Frequency

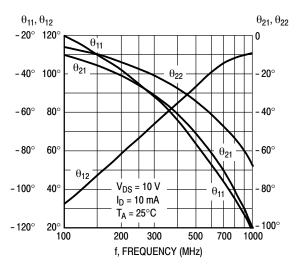


Figure 7. S Parameter Phase–Angle versus Frequency



SOT-23 (TO-236) CASE 318-08 **ISSUE AS**

DATE 30 JAN 2018

SCALE 4:1 D - 3X b

TOP VIEW







RECOMMENDED SOLDERING FOOTPRINT



DIMENSIONS: MILLIMETERS

NOTES:

- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH.
 MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL
- 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH,

	PROT	RUSIONS, OR GATE BURRS.	
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	MILLIMETERS				INCHES	
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.039	0.044
A1	0.01	0.06	0.10	0.000	0.002	0.004
b	0.37	0.44	0.50	0.015	0.017	0.020
С	0.08	0.14	0.20	0.003	0.006	0.008
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.080
L	0.30	0.43	0.55	0.012	0.017	0.022
L1	0.35	0.54	0.69	0.014	0.021	0.027
HE	2.10	2.40	2.64	0.083	0.094	0.104
Т	0°		10°	0°		10°

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code

= Date Code

= Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

STYLE 1 THRU 5: CANCELLED	STYLE 6: PIN 1. BASE 2. EMITTER 3. COLLECTOR	STYLE 7: PIN 1. EMITTER 2. BASE 3. COLLECTOR	STYLE 8: PIN 1. ANODE 2. NO CONNECTION 3. CATHODE
OT (1 F O			

SOT-23 (TO-236)

STYLE 9:	STYLE 10:	STYLE 11:	STYLE 12:	STYLE 13:	STYLE 14:
PIN 1. ANODE	PIN 1. DRAIN	PIN 1. ANODE	PIN 1. CATHODE	PIN 1. SOURCE	PIN 1. CATHODE
ANODE	SOURCE	CATHODE	CATHODE	2. DRAIN	2. GATE
CATHODE	3. GATE	CATHODE-ANODE	ANODE	3. GATE	ANODE

STYLE 15:	STYLE 16:	STYLE 17:	STYLE 18:	STYLE 19:	STYLE 20:
PIN 1. GATE	PIN 1. ANODE	PIN 1. NO CONNECTION	PIN 1. NO CONNECTION	PIN 1. CATHODE	PIN 1. CATHODE
CATHODE	CATHODE	2. ANODE	CATHODE	2. ANODE	ANODE
ANODE	CATHODE	CATHODE	ANODE	CATHODE-ANOD	E 3. GATE

STYLE 21:	STYLE 22:	STYLE 23:	STYLE 24:	STYLE 25:	STYLE 26:
PIN 1. GATE	PIN 1. RETURN	PIN 1. ANODE	PIN 1. GATE	PIN 1. ANODE	PIN 1. CATHODE
SOURCE	OUTPUT	2. ANODE	2. DRAIN	2. CATHODE	2. ANODE
3 DRAIN	3 INPLIT	3 CATHODE	3. SOURCE	3. GATE	NO CONNECTION

STYLE 27: PIN 1. CATHODE 2. CATHODE 3. CATHODE	STYLE 28: PIN 1. ANODE 2. ANODE 3. ANODE	
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